

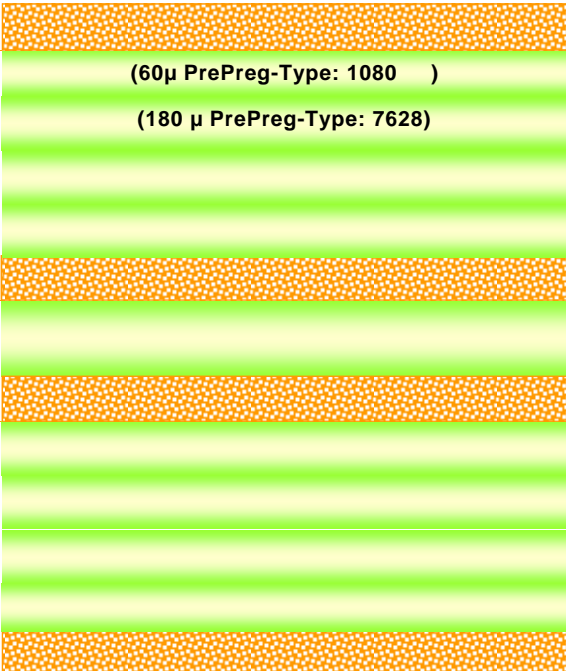
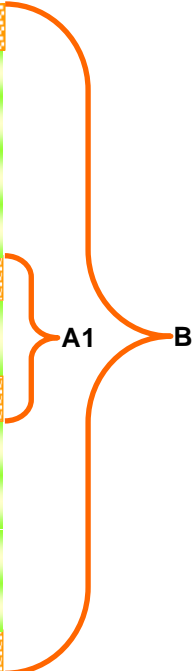
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 154 FR4 35 L20.35 P18_06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_154_FR4_35_L20.35_p18_06

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	60 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	35 μ	Copper		
	200 μ	L-FR4		
Layer-3	35 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
	60 μ	Prepreg		
Layer-99	35 μ	Copper		

© Copyright by Printed Circuit Boards GmbH